

PATENT ASSIGNMENT

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hsiao-Tzu Lu	03/28/2005
Chin-Hsiang Lin	03/28/2005
Hua-Shu Wu	03/28/2005
Chia-Hsiang Lin	03/28/2005
Kuei Shun Chen	03/28/2005

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11099966

CORRESPONDENCE DATA

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Total Attachments: 3

500033343

PATENT
REEL: 016071 FRAME: 0190

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ASSIGNMENT

WHEREAS, we,

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|-----|-----------------|----|--------------------------|
| (1) | Hsiao-Tzu Lu | of | Hsin-Chu, Taiwan, R.O.C. |
| (2) | Chin-Hsiang Lin | of | Hsin-Chu, Taiwan, R.O.C. |
| (3) | Hua-Shu Wu | of | Hsin-Chu, Taiwan, R.O.C. |
| (4) | Chia-Hsiang Lin | of | Hsin-Chu, Taiwan, R.O.C. |
| (5) | Kuei Shun Chen | of | Hsin-Chu, Taiwan, R.O.C. |

have invented certain improvements in

A SYSTEM AND METHOD FOR OVERLAY MEASUREMENT IN SEMICONDUCTOR MANUFACTURING

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on April 6, 2005 and assigned application number 11/099,966; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

Docket No.: 2004-0808 / 24061.588

Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Hsiao-Tzu LuResidence Address: (address) No. 11, 132 Alley, Cha-t - Chiao Rd.,
Hsin-Chu, Taiwan 300, R.O.C.
Taiwan, R.O.C.Dated: 3/28/05✓ Hsiao-Tzu Lu
Inventor Signature

Inventor Name: Chin-Hsiang LinResidence Address: (address) No. 37, Lane 393, Hsin-hu Rd.,
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Docket No.: 2004-0808 / 24061.588

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✓ Chia-Hsiang Lin
Inventor Signature

Inventor Name: Kuei Shun ChenResidence Address: (address) 5F, No. 22, Lane 634, Nan-Da Rd.,
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Dated: ✓ 3/28/2005

✓ Kuei Shun Chen
Inventor Signature

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